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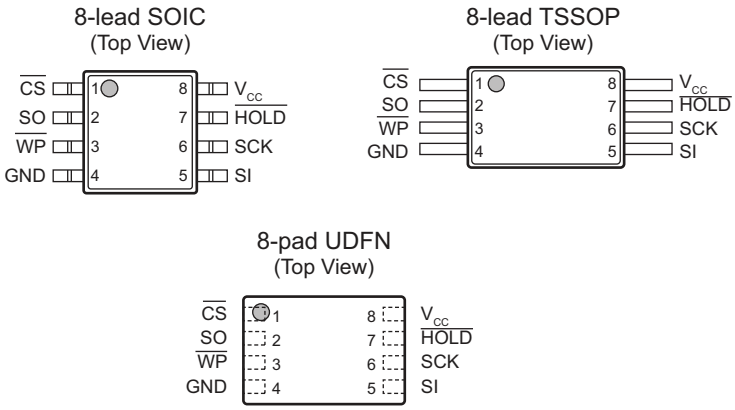
1. Pin Configurations and Pinouts

Figure 1. Pin Configurations

Pin Name	Function
$\overline{CS}$	Chip Select
SCK	Serial Data Clock
SI	Serial Data Input
SO	Serial Data Output
GND	Ground
V_{CC}	Power Supply
$\overline{WP}$	Write Protect
$\overline{HOLD}$	Suspends Serial Input



Note: Drawings are not to scale.

2. Absolute Maximum Ratings*

Operating Temperature	-40°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on any pin with respect to ground	-1.0V to +7.0V
Maximum Operating Voltage	6.25V
DC Output Current	5.0mA

*Notice: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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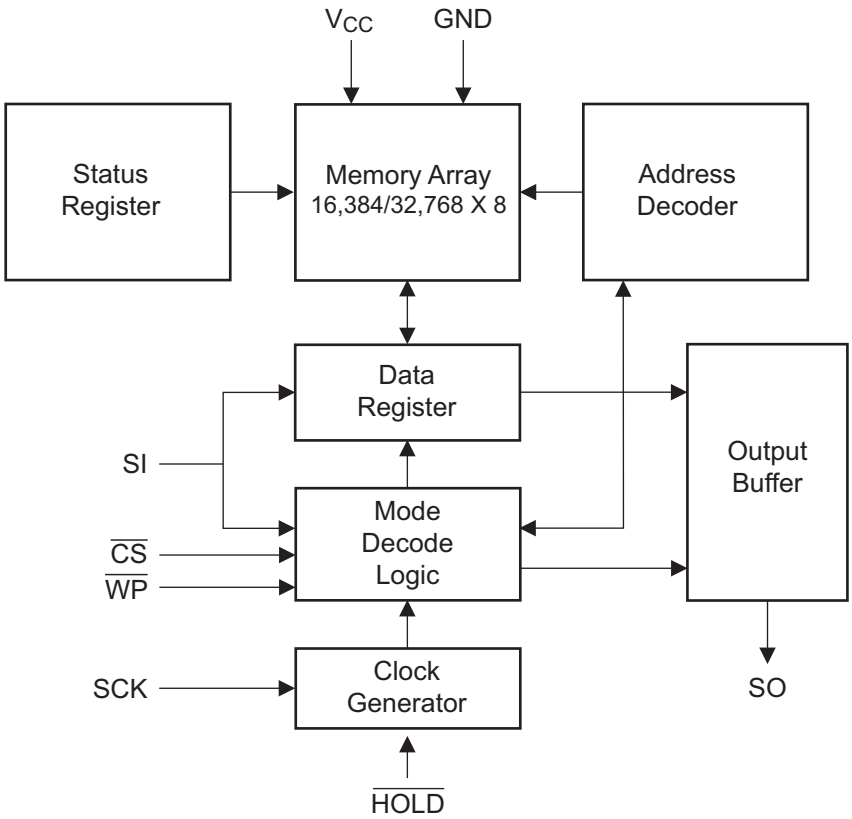
3. Block Diagram

Figure 3-1. Block Diagram



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4. Serial Interface Description

Master: The device that generates the serial clock.

Slave: Because the Serial Clock pin (SCK) is always an input, AT25128B/256B always operates as a slave.

Transmitter/Receiver: AT25128B/256B has separate pins designated for data transmission (SO) and reception (SI).

MSB: The Most Significant Bit (MSB) is the first bit transmitted and received.

Serial Opcode: After the device is selected with $\overline{CS}$ going low, the first byte will be received. This byte contains the opcode that defines the operations to be performed.

Invalid Opcode: If an invalid opcode is received, no data will be shifted into AT25128B/256B, and the Serial Output pin (SO) will remain in a high impedance state until the falling edge of $\overline{CS}$ is detected again. This will reinitialize the serial communication.

Chip Select: AT25128B/256B is selected when the $\overline{CS}$ pin is low. When the device is not selected, data will not be accepted via the SI pin, and the Serial Output pin (SO) will remain in a high impedance state.

Hold: The $\overline{HOLD}$ pin is used in conjunction with the $\overline{CS}$ pin to select AT25128B/256B. When the device is selected and a serial sequence is underway, $\overline{HOLD}$ can be used to pause the serial communication with the master device without resetting the serial sequence. To pause, the $\overline{HOLD}$ pin must be brought low while the SCK pin is low. To resume serial communication, the $\overline{HOLD}$ pin is brought high while the SCK pin is low (SCK may still toggle during $\overline{HOLD}$). Inputs to the SI pin will be ignored while the SO pin is in the high impedance state.

Write Protect: The Write Protect pin ($\overline{WP}$) will allow normal read/write operations when held high. When the WP pin is brought low and WPEN bit is one, all write operations to the Status Register are inhibited. $\overline{WP}$ going low while $\overline{CS}$ is still low will interrupt a write to the Status Register. If the internal write cycle has already been initiated, $\overline{WP}$ going low will have no effect on any write operation to the Status Register. The $\overline{WP}$ pin function is blocked when the WPEN bit in the Status Register is zero. This will allow the user to install AT25128B/256B in a system with the $\overline{WP}$ pin tied to ground and still be able to write to the Status Register. All $\overline{WP}$ pin functions are enabled when the WPEN bit is set to one.

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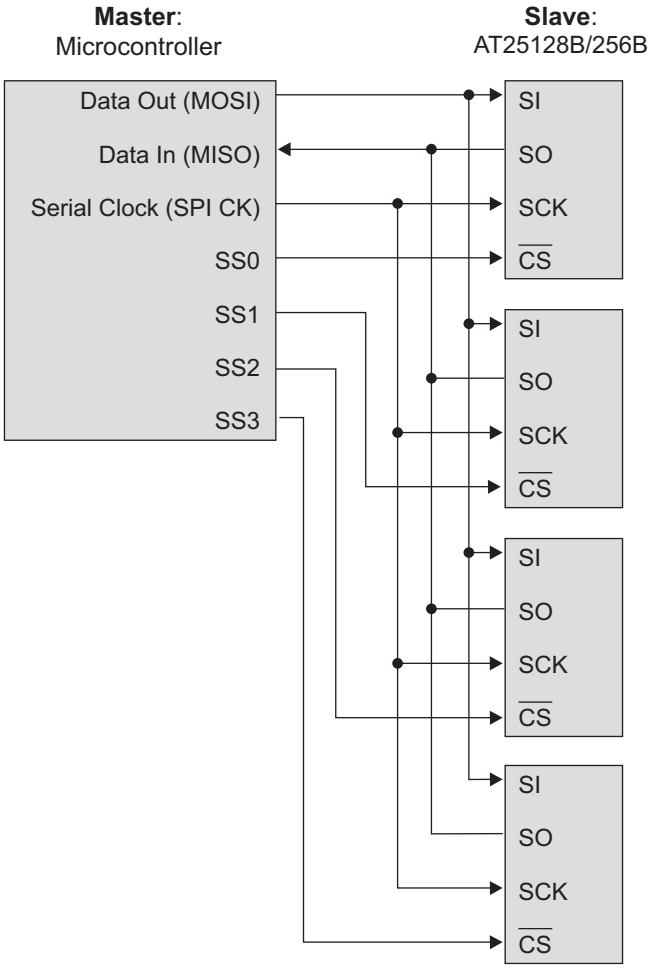
Figure 4-1. SPI Serial Interface



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5. Electrical Characteristics

5.1 Pin Capacitance

Table 5-1. Pin Capacitance[1]

Applicable at these conditions, unless otherwise noted. T_A = 25°C, f = 1.0MHz, V_{CC} = +5.0V.

Symbol	Test Conditions	Max	Units	Conditions
C_{OUT}	Output Capacitance (SO)	8	pF	V_{OUT} = 0V
C_{IN}	Input Capacitance ($\overline{CS}$, SCK, SI, $\overline{WP}$, $\overline{HOLD}$)	6	pF	V_{IN} = 0V

Note: 1. This parameter is characterized and is not 100% tested.

5.2 DC Characteristics

Table 5-2. DC Characteristics

Applicable over recommended operating range from: T_{A1} = -40°C to +125°C, V_{CC1} = 2.5V to 5.5V;
T_{A2} = -40°C to 105°C, V_{CC2} = 1.7V to 5.5V.

Symbol	Parameter	Test Condition		Min	Typ	Max	Units
V_{CC1}	Supply Voltage	Grade 1		2.5		5.5	V
V_{CC2}		Grade 2[2] and 3		1.7		5.5	
I_{CC1}	Supply Current	V_{CC} = 5.0V at 5MHz, SO = Open, Read				6	mA
I_{CC2}		V_{CC} = 5.0V at 1MHz, SO = Open, Read, Write				3	
I_{CC3}		V_{CC} = 5.0V at 5MHz, SO = Open, Read, Write				7	
I_{SB1}	Standby Current	V_{CC} = 1.7V	$\overline{CS}$ = V_{CC}		0.1	9	µA
I_{SB2}		V_{CC} = 2.5V			0.2	10	
I_{SB3}		V_{CC} = 5.0V			2.0	13	
I_{IL}	Input Leakage	V_{IN} = 0V to V_{CC}		-3		3	µA
I_{OL}	Output Leakage	V_{IN} = 0V to V_{CC}		-3		3	
V_{IL}[1]	Input Low-voltage			-0.6		V_{CC} x 0.3	V
V_{IH}[1]	Input High-voltage			V_{CC} x 0.7		V_{CC} + 0.5	
V_{OL1}	Output Low-voltage	2.5V ≤ V_{CC} ≤ 5.5V	I_{OL} = 3.0mA			0.4	V
V_{OH1}	Output High-voltage		I_{OH} = -1.6mA	V_{CC} – 0.8			
V_{OL2}	Output Low-voltage	1.7V ≤ V_{CC} ≤ 5.5V	I_{OL} = 0.15mA			0.2	V
V_{OH2}	Output High-voltage		I_{OH} = -100µA	V_{CC} – 0.2			

Notes: 1. V_{IL} min and V_{IH} max are reference only and are not tested.
2. Contact Sales for Grade 2 Availability

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5.3 AC Characteristics

Table 5-3. AC Characteristics

Applicable over recommended operating range from T_A = -40°C to +125°C, V_{CC} = As Specified, CL = 1 TTL Gate and 100pF (unless otherwise noted).

Symbol	Parameter	Voltage	Min	Max	Units
f_{SCK}	SCK Clock Frequency	1.7 to 5.5	0	5.0	MHz
t_{RI}	Input Rise Time	1.7 to 5.5		2	µs
t_{FI}	Input Fall Time	1.7 to 5.5		2	µs
t_{WH}	SCK High Time	1.7 to 5.5	40		ns
t_{WL}	SCK Low Time	1.7 to 5.5	40		ns
t_{CS}	$\overline{CS}$ High Time	1.7 to 5.5	80		ns
t_{CSS}	$\overline{CS}$ Setup Time	1.7 to 5.5	80		ns
t_{CSH}	$\overline{CS}$ Hold Time	1.7 to 5.5	80		ns
t_{SU}	Data In Setup Time	1.7 to 5.5	5		ns
t_H	Data In Hold Time	1.7 to 5.5	20		ns
t_{HD}	$\overline{Hold}$ Setup Time	1.7 to 5.5	40		ns
t_{CD}	$\overline{Hold}$ Hold Time	1.7 to 5.5	40		ns
t_V	Output Valid	1.7 to 5.5	0	40	ns
t_{HO}	Output Hold Time	1.7 to 5.5	0		ns
t_{LZ}	$\overline{Hold}$ to Output Low Z	1.7 to 5.5	0	40	ns
t_{HZ}	$\overline{Hold}$ to Output High Z	1.7 to 5.5		80	ns
t_{DIS}	Output Disable Time	1.7 to 5.5		80	ns
t_{WC}	Write Cycle Time	1.7 to 5.5		5	ms
Endurance(1)	5.0V, 25°C, Page Mode		1,000,000		Write Cycles

Note: 1. This parameter is characterized and is not 100% tested.

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6. Functional Description

AT25128B/256B is designed to interface directly with the synchronous Serial Peripheral Interface (SPI) of the 6805 and 68HC11 series of microcontrollers.

AT25128B/256B utilizes an 8-bit instruction register. The list of instructions and their operation codes are contained in the table below. All instructions, addresses, and data are transferred with the MSB first and start with a high-to-low CS transition.

Table 6-1. AT25128B/256B Instruction Set

Instruction Name	Instruction Format	Operation
WREN	0000 X110	Set Write Enable Latch
WRDI	0000 X100	Reset Write Enable Latch
RDSR	0000 X101	Read Status Register
WRSR	0000 X001	Write Status Register
READ	0000 X011	Read Data from Memory Array
WRITE	0000 X010	Write Data to Memory Array

Write Enable (WREN): The device will power up in the write disable state when V_{CC} is applied. All programming instructions must therefore be preceded by a Write Enable instruction.

Write Disable (WRDI): To protect the device against inadvertent writes, the Write Disable instruction disables all programming modes. The WRDI instruction is independent of the status of the $\overline{WP}$ pin.

Read Status Register (RDSR): The Read Status Register instruction provides access to the Status Register. The Ready/Busy and Write Enable status of the device can be determined by the RDSR instruction. Similarly, the block write protection bits indicate the extent of protection employed. These bits are set by using the WRSR instruction.

Table 6-2. Status Register Format

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
WPEN	X	X	X	BP1	BP0	WEN	$\overline{RDY}$

Table 6-3. Read Status Register Bit Definition

Bit	Definition
Bit 0 ($\overline{RDY}$)	Bit 0 = 0 ($\overline{RDY}$) indicates the device is ready. Bit 0 = 1 indicates the write cycle is in progress.
Bit 1 (WEN)	Bit 1= 0 indicates the device is not write-enabled. Bit 1 = 1 indicates the device is write-enabled.
Bit 2 (BP0)	See Table 6-4 on page 10.
Bit 3 (BP1)	See Table 6-4 on page 10.
Bits 4 – 6 are zeros when device is not in an internal write cycle.	
Bit 7 (WPEN)	See Table 6-5 on page 10.

Note: 1. Bits 0 - 7 are ones during the internal write cycle.

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Write Status Register (WRSR): The WRSR instruction allows the user to select one of four levels of protection. AT25128B/256B is divided into four array segments. One-quarter, one-half, or all of the memory segments can be protected. Any of the data within any selected segment will therefore be read-only. The block write protection levels and corresponding Status Register control bits are shown in the table below.

Bits BP0, BP1, and WPEN are nonvolatile cells that have the same properties and functions as the regular memory cells (e.g., WREN, t_{WC}, RDSR).

Table 6-4. Block Write Protect Bits

Level	Status Register Bits		Array Addresses Protected	
	BP1	BP0	AT25128B	AT25256B
0	0	0	None	None
1 (1/4)	0	1	3000 – 3FFF	6000 – 7FFF
2 (1/2)	1	0	2000 – 3FFF	4000 – 7FFF
3 (All)	1	1	0000 – 3FFF	0000 – 7FFF

The WRSR instruction also allows the user to enable or disable the Write Protect ($\overline{WP}$) pin through the use of the Write Protect Enable (WPEN) bit. Hardware write protection is enabled when the $\overline{WP}$ pin is low and the WPEN bit is one. Hardware write protection is disabled when either the $\overline{WP}$ pin is high or the WPEN bit is zero. When the device is hardware write protected, writes to the Status Register, including the block protect bits and the WPEN bit, and the block-protected sections in the memory array are disabled. Writes are only allowed to sections of the memory that are not block-protected.

Note: When the WPEN bit is hardware write protected, it cannot be changed back to zero as long as the $\overline{WP}$ pin is held low.

Table 6-5. WPEN Operation

WPEN	$\overline{WP}$	WEN	Protected Blocks	Unprotected Blocks	Status Register
0	X	0	Protected	Protected	Protected
0	X	1	Protected	Writeable	Writeable
1	Low	0	Protected	Protected	Protected
1	Low	1	Protected	Writeable	Protected
X	High	0	Protected	Protected	Protected
X	High	1	Protected	Writeable	Writeable

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Read Sequence (READ): Reading the AT25128B/256B via the Serial Output (SO) pin requires the following sequence. After the $\overline{CS}$ line is pulled low to select a device, the read opcode is transmitted via the SI line followed by the byte address to be read (A15–A0, see the table below). Upon completion, any data on the SI line will be ignored. The data (D7–D0) at the specified address is then shifted out onto the SO line. If only one byte is to be read, the $\overline{CS}$ line should be driven high after the data comes out. The read sequence can be continued since the byte address is automatically incremented and data will continue to be shifted out. When the highest address is reached, the address counter will roll over to the lowest address, allowing the entire memory to be read in one continuous read cycle.

Write Sequence (WRITE): In order to program the AT25128B/256B, two separate instructions must be executed. First, the device ***must be write enabled*** via the WREN instruction. Then a Write (WRITE) instruction may be executed. Also, the address of the memory location(s) to be programmed must be outside the protected address field location selected by the block write protection level. During an internal write cycle, all commands will be ignored except the RDSR instruction.

A Write instruction requires the following sequence. After the $\overline{CS}$ line is pulled low to select the device, the WRITE opcode is transmitted via the SI line followed by the byte address (A15–A0) and the data (D7–D0) to be programmed (See the table below). Programming will start after the $\overline{CS}$ pin is brought high. The low-to-high transition of the $\overline{CS}$ pin must occur during the SCK low-time immediately after clocking in the D0 (LSB) data bit.

The Ready/Busy status of the device can be determined by initiating a Read Status Register (RDSR) instruction. If Bit 0 = one, the write cycle is still in progress. If Bit 0 = zero, the write cycle has ended. Only the RDSR instruction is enabled during the write programming cycle.

AT25128B/256B is capable of a 64-byte page write operation. After each byte of data is received, the six bits will resolve 64 address; low-order address bits are internally incremented by one; and the high-order bits of the address will remain constant. If more than 64 bytes of data are transmitted, the address counter will roll over and the previously written data will be overwritten. AT25128B/256B is automatically returned to the write disable state at the completion of a write cycle.

Note: If the device is not Write Enabled (WREN), the device will ignore the write instruction and will return to the standby state, when $\overline{CS}$ is brought high. A new $\overline{CS}$ falling edge is required to reinitiate the serial communication.

Table 6-6. Address Key

Address	AT25128B	AT25256B
A_N	A_{13}–A_0	A_{14}–A_0
Don't Care Bits	A_{15}–A_{14}	A_{15}

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7. Timing Diagrams

Figure 7-1. Synchronous Data Timing (for Mode 0)

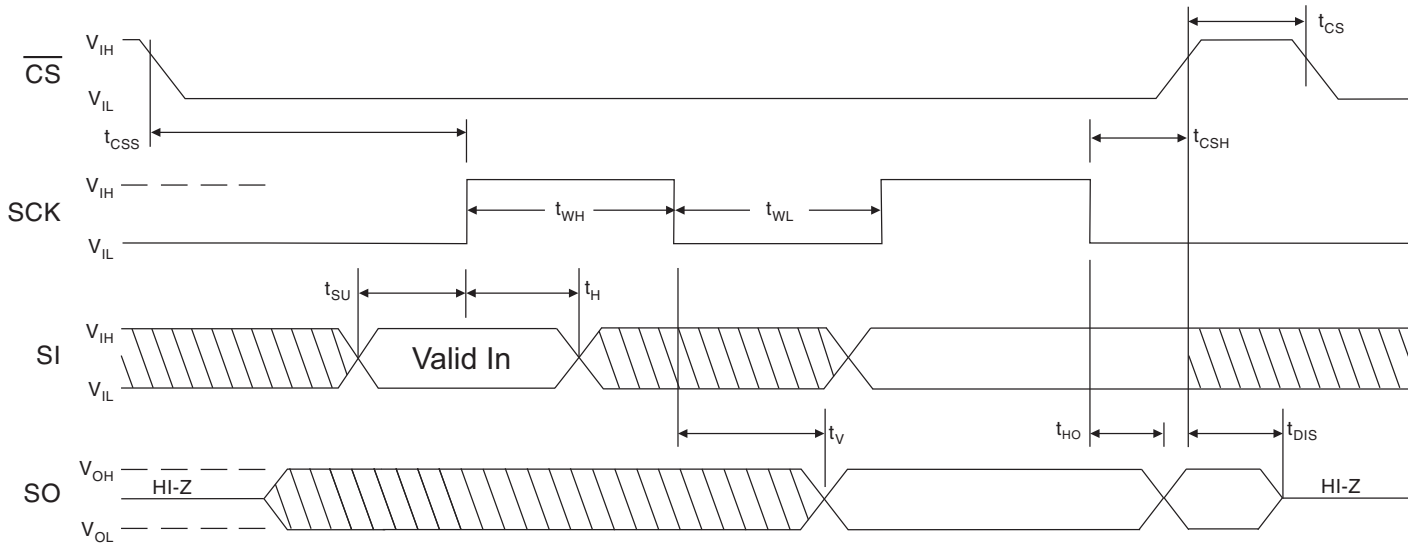

Figure 7-2. WREN Timing

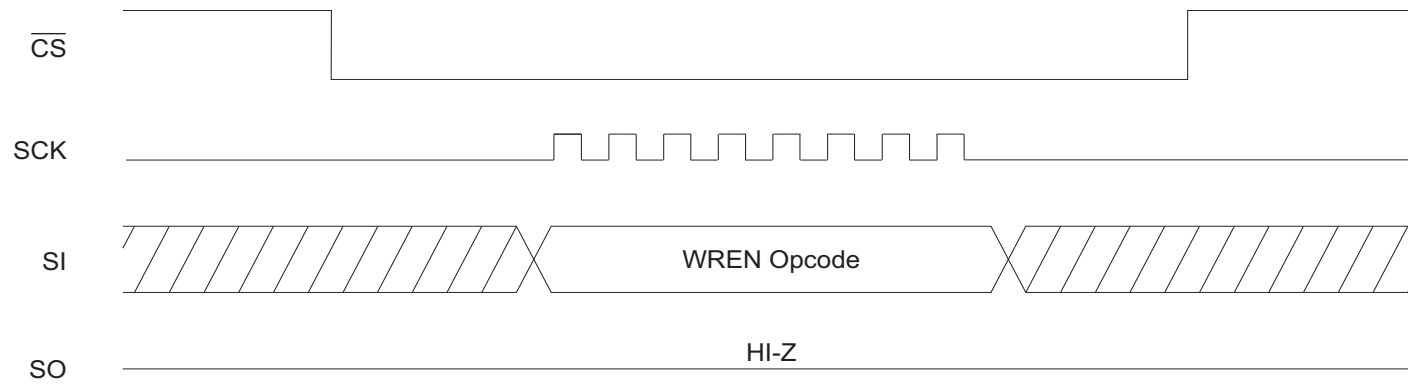

Figure 7-3. WRDI Timing

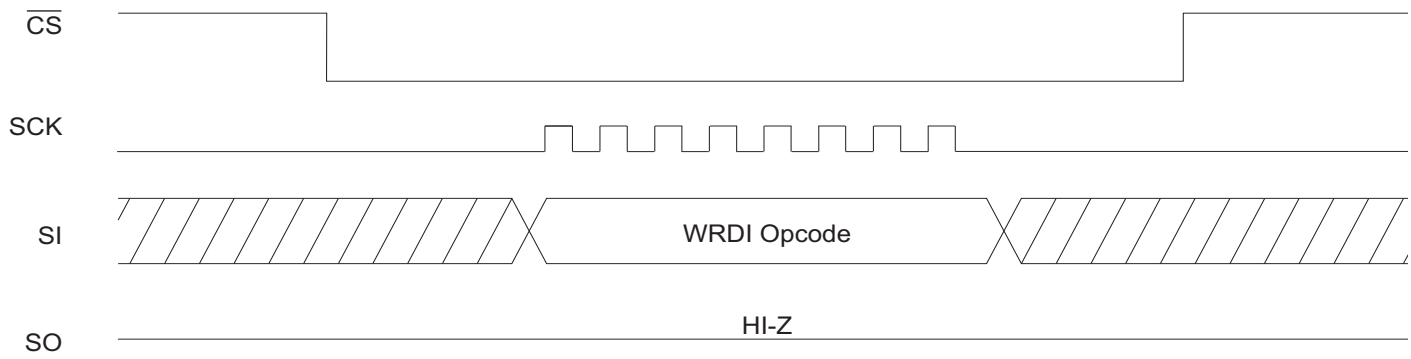

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Figure 7-4. RDSR Timing

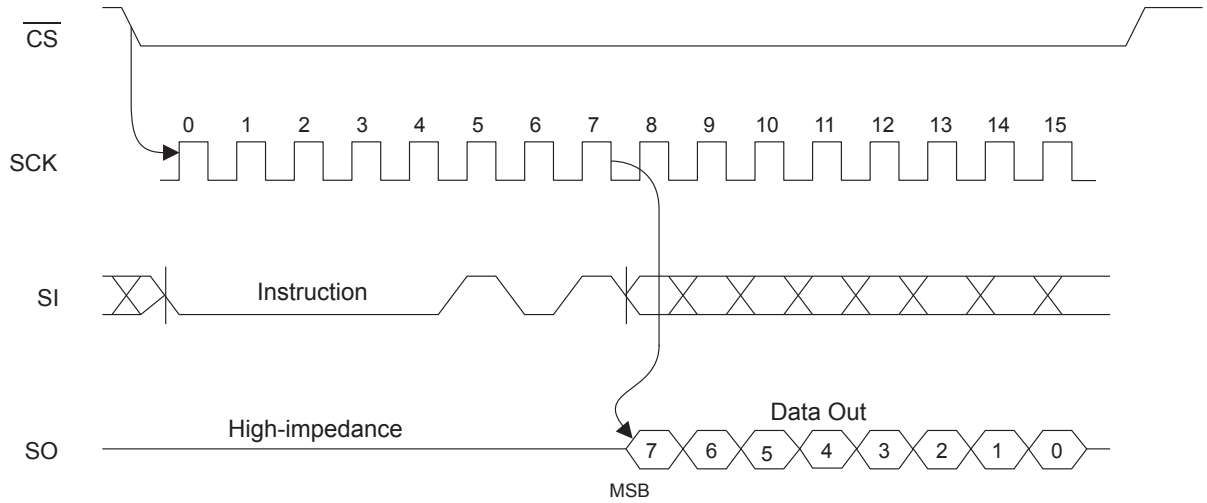

Figure 7-5. WRSR Timing

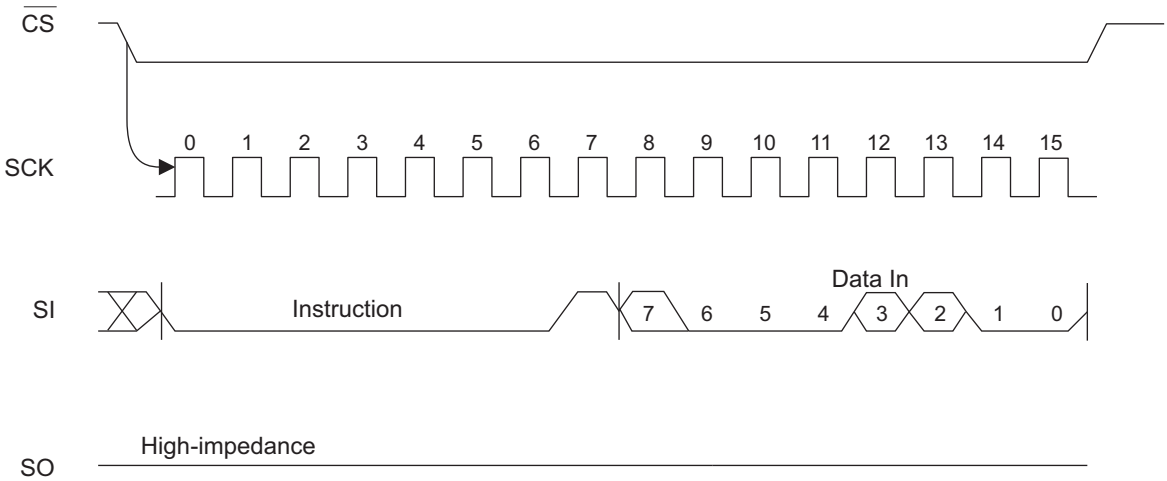

Figure 7-6. Read Timing

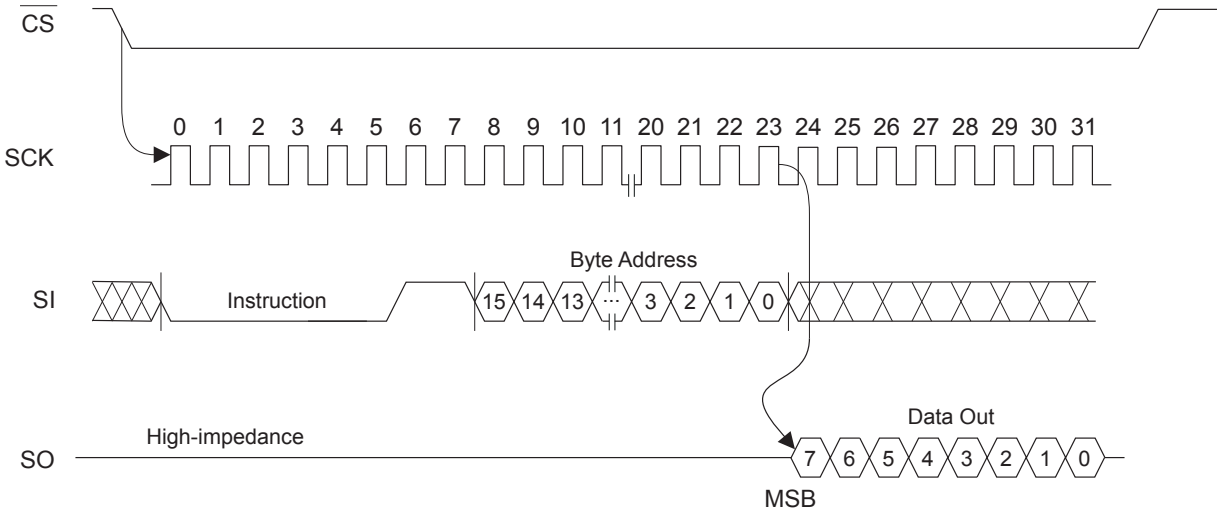

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Figure 7-7. Write Timing

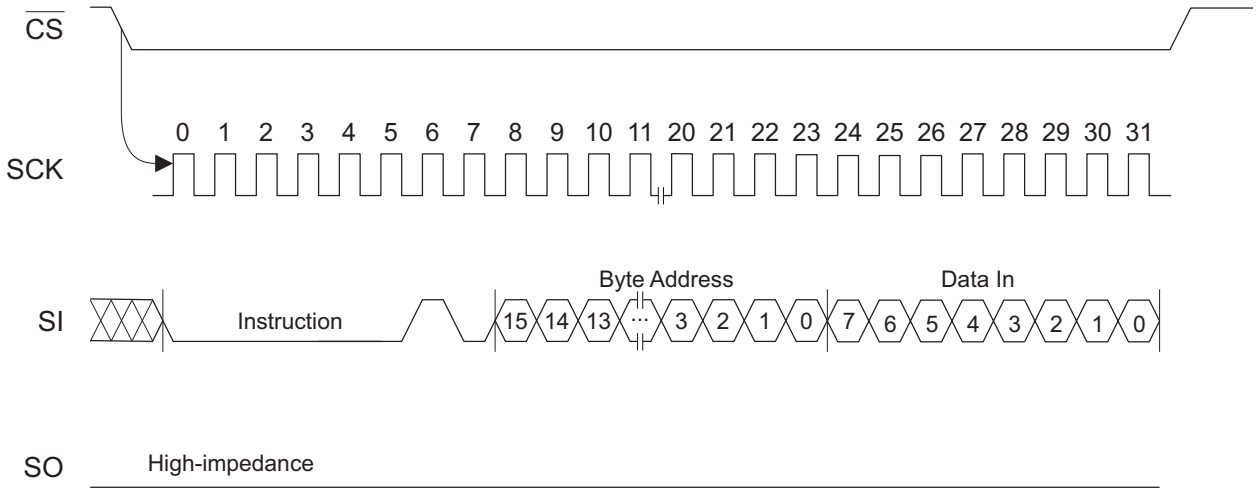
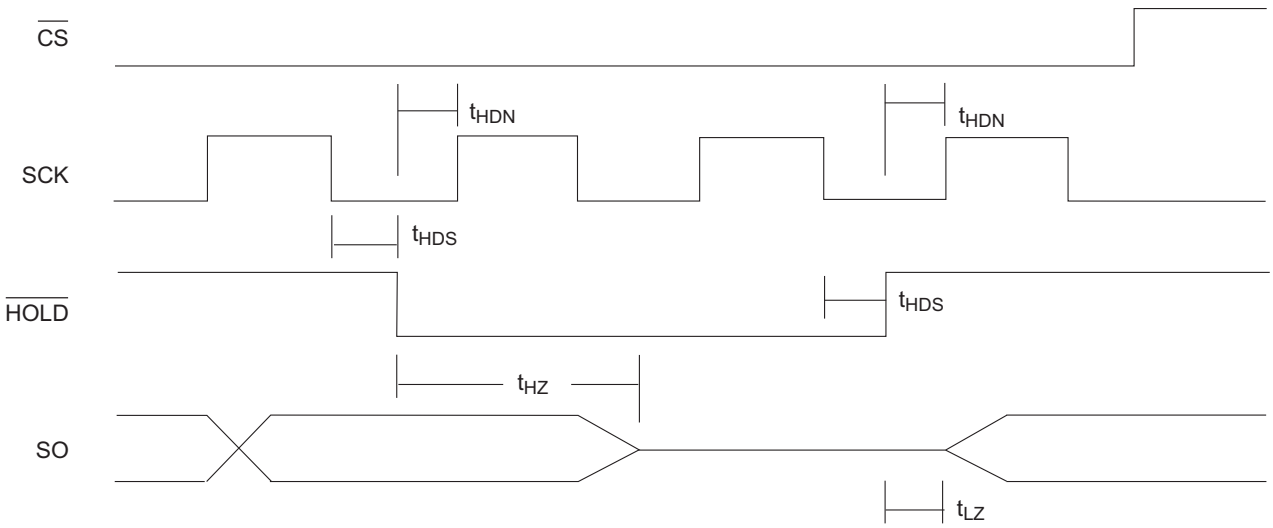


Figure 7-8. $\overline{\text{HOLD}}$ Timing



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7.1 Power Recommendation

The device internal POR (Power-On Reset) threshold is just below the minimum device operating voltage.

Power shall rise monotonically from 0.0Vdc to full V_{CC} in less than 1ms. Hold at full V_{CC} for at least 100µs before the first operation. Power shall drop from full V_{CC} to 0.0Vdc in less than 1ms. Power shall remain off (0.0Vdc) for 0.03ms minimum. Power dropping to a non-zero level and then slowly going to zero is not recommended, but if unavoidable the V_{CC} level supplied to the part must remain below 0.5V for at least 0.1ms to ensure a proper reset.

Please consult Atmel if your power conditions do not meet the above recommendations.

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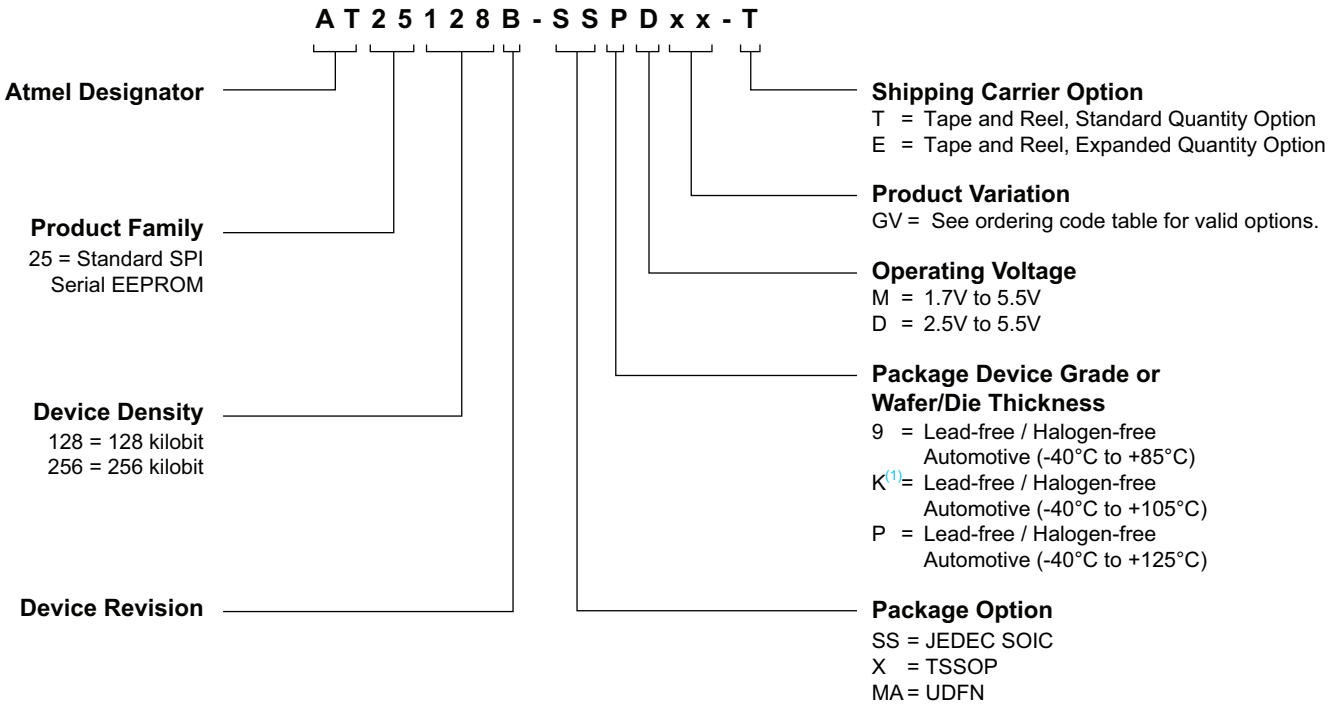
8. Ordering Information

8.1 Ordering Code Detail



Note: 1. Contact Sales for Grade 2 Availability

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8.2 Ordering Code Information

8.2.1 Automotive Grade 1, V_{CC} = 2.5V to 5.5V

Atmel Ordering Code	Lead Finish	Package	Delivery Information		Operation Range
			Form	Quantity	
AT25128B-SSPDGV-T	NiPdAu (Lead-free/Halogen-free)	8S1	Tape and Reel	4,000 per Reel	Automotive Temperature (-40°C to 125°C)
AT25128B-XPDGV-T		8X		5,000 per Reel	
AT25128B-MAPDGV-T		8MA2		5,000 per Reel	
AT25128B-MAPDGV-E				15,000 per Reel	
AT25256B-SSPDGV-T	NiPdAu (Lead-free/Halogen-free)	8S1	Tape and Reel	4,000 per Reel	Automotive Temperature (-40°C to 125°C)
AT25256B-XPDGV-T		8X		5,000 per Reel	
AT25256B-MAPDGV-T		8MA2		5,000 per Reel	
AT25256B-MAPDGV-E				15,000 per Reel	

Package Type	
8S1	8-lead, 0.150" wide, Plastic Gull Wing Small Outline (JEDEC SOIC)
8X	8-lead 4.4mm body, Plastic Thin Shrink Small Outline (TSSOP)
8MA2	8-pad, 2.00mm x 3.00mm body, 0.50mm pitch, Ultra Thin, Dual No Lead (UDFN)

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8.2.2 Automotive Grade 3, V_{CC} = 1.7V to 5.5V

Atmel Ordering Code	Lead Finish	Package	Delivery Information		Operation Range
			Form	Quantity	
AT25128B-SS9MGV-T	NiPdAu (Lead-free/Halogen-free)	8S1	Tape and Reel	4,000 per Reel	Automotive Temperature (-40°C to 85°C)
AT25128B-X9MGV-T		8X		5,000 per Reel	
AT25128B-MA9MGV-T		8MA2		5,000 per Reel	
AT25128B-MA9MGV-E				15,000 per Reel	
AT25256B-SS9MGV-T	NiPdAu (Lead-free/Halogen-free)	8S1	Tape and Reel	4,000 per Reel	Automotive Temperature (-40°C to 85°C)
AT25256B-X9MGV-T		8X		5,000 per Reel	
AT25256B-MA9MGV-T		8MA2		5,000 per Reel	
AT25256B-MA9MGV-E				15,000 per Reel	

Package Type	
8S1	8-lead, 0.150" wide, Plastic Gull Wing Small Outline (JEDEC SOIC)
8X	8-lead 4.4mm body, Plastic Thin Shrink Small Outline (TSSOP)
8MA2	8-pad, 2.00mm x 3.00mm body, 0.50mm pitch, Ultra Thin, Dual No Lead (UDFN)

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8.2.3 Legacy Ordering Code Information (Not Recommended for New Designs, NRND)

Atmel Ordering Code	Lead Finish	Package	Delivery Information		Operation Range
			Form	Quantity	
AT25128B-SSPD-T	NiPdAu (Lead-free/Halogen-free)	8S1	Tape and Reel	4,000 per Reel	Automotive Temperature (–40°C to 125°C)
AT25128B-XPD-T		8X		5,000 per Reel	
AT25256B-SSPD-T	NiPdAu (Lead-free/Halogen-free)	8S1	Tape and Reel	4,000 per Reel	Automotive Temperature (–40°C to 125°C)
AT25256B-XPD-T		8X		5,000 per Reel	

Package Type	
8S1	8-lead, 0.150" wide, Plastic Gull Wing Small Outline (JEDEC SOIC)
8X	8-lead 4.4mm body, Plastic Thin Shrink Small Outline (TSSOP)
8MA2	8-pad, 2.00mm x 3.00mm body, 0.50mm pitch, Ultra Thin, Dual No Lead (UDFN)

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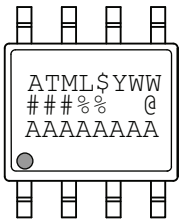
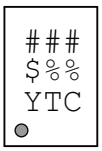
8.3 Part Markings

AT25128B and AT25256B: Automotive Package Marking Information

8-lead SOIC	8-lead TSSOP	8-pad UDFN
		2.0 x 3.0 mm Body 

Note 1: ● designates pin 1

Note 2: Package drawings are not to scale

Catalog Number Truncation			
AT25128B		Truncation Code ###:	5DB
AT25256B		Truncation Code ###:	5EB

Date Codes				**%% = Voltages**
Y = Year		M = Month	WW = Work Week of Assembly	M: 1.7V minimum
6: 2016	0: 2020	A: January	02: Week 2	D: 2.5V minimum
7: 2017	1: 2021	B: February	04: Week 4	GV: GV Product Variation
8: 2018	2: 2022	...	...	
9: 2019	3: 2023	L: December	52: Week 52	

Country of Assembly	**Lot Number**	**$ = Grade/Lead Finish Material**
@ = Country of Assembly	AAA...A = Atmel Wafer Lot Number	P: Automotive Grade 1/NiPdAu K: Automotive Grade 2/NiPdAu 9: Automotive Grade 3/NiPdAu

Trace Code	**Atmel Truncation**
TC = Trace Code (Atmel Lot Numbers Correspond to Code) Example: AA, AB.... YZ, ZZ	AT: Atmel ATM: Atmel ATML: Atmel

4/12/2016

Atmel Package Mark Contact: DL-CSO-Assy_eng@atmel.com	TITLE	DRAWING NO.	REV.
	25128-256BAM, AT25128B and AT25256B Automotive Package Marking Information	25128-256BAM	E

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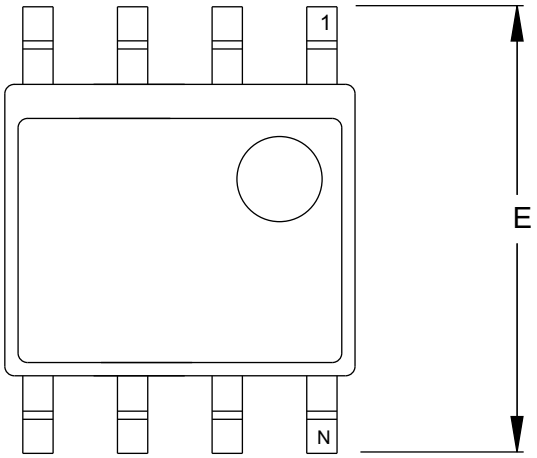
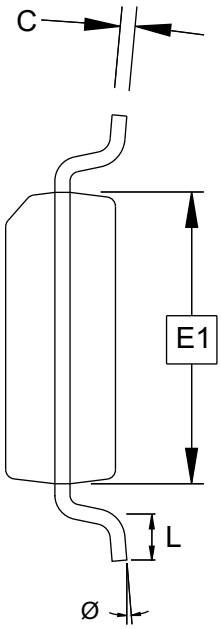
9. Packaging Information

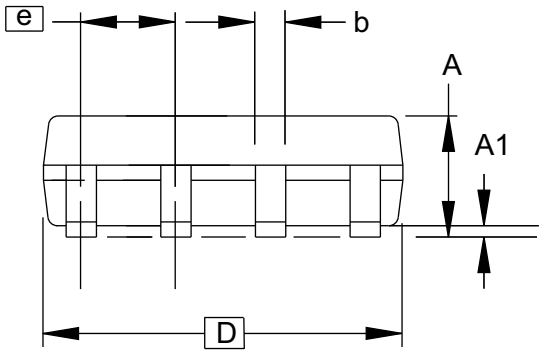
9.1 8S1 — 8-lead JEDEC SOIC



TOP VIEW



END VIEW



SIDE VIEW

Notes: This drawing is for general information only.
Refer to JEDEC Drawing MS-012, Variation AA
for proper dimensions, tolerances, datums, etc.

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.75	
A1	0.10	–	0.25	
b	0.31	–	0.51	
C	0.17	–	0.25	
D		4.90 BSC		
E		6.00 BSC		
E1		3.90 BSC		
e		1.27 BSC		
L	0.40	–	1.27	
Ø	0°	–	8°	

3/6/2015

Atmel Package Drawing Contact: packagedrawings@atmel.com	**TITLE** 8S1, 8-lead (0.150” Wide Body), Plastic Gull Wing Small Outline (JEDEC SOIC)	**GPC** SWB	**DRAWING NO.** 8S1	**REV.** H

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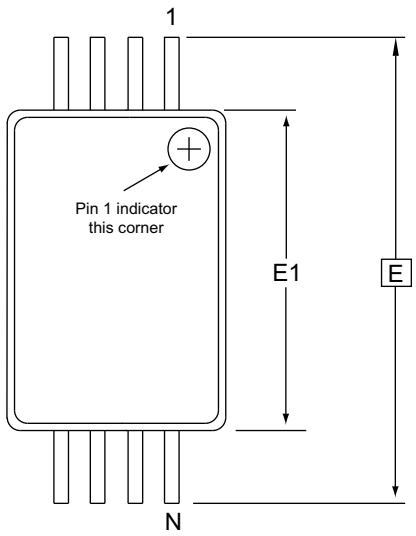
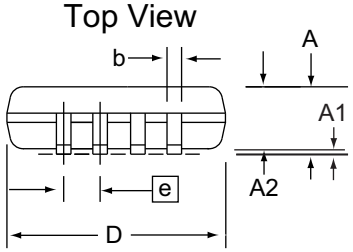
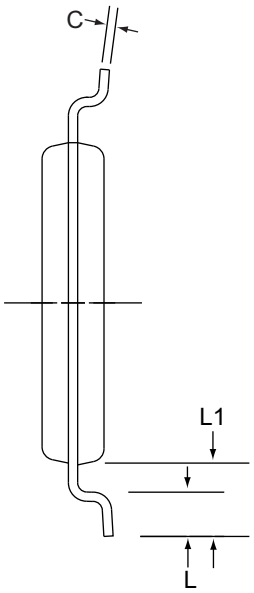
9.2 8X — 8-lead TSSOP



Top View



Side View



End View

Notes:
1. This drawing is for general information only. Refer to JEDEC Drawing MO-153, Variation AA, for proper dimensions, tolerances, datums, etc.
2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15mm (0.006in) per side.
3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25mm (0.010in) per side.
4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07mm.
5. Dimension D and E1 to be determined at Datum Plane H.

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-	-	1.20	
A1	0.05	-	0.15	
A2	0.80	1.00	1.05	
D	2.90	3.00	3.10	2, 5
E		6.40 BSC		
E1	4.30	4.40	4.50	3, 5
b	0.19	0.25	0.30	4
e		0.65 BSC		
L	0.45	0.60	0.75	
L1		1.00 REF		
C	0.09	-	0.20	

2/27/14

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE 8X, 8-lead 4.4mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)	GPC TNR	DRAWING NO. 8X	REV. E

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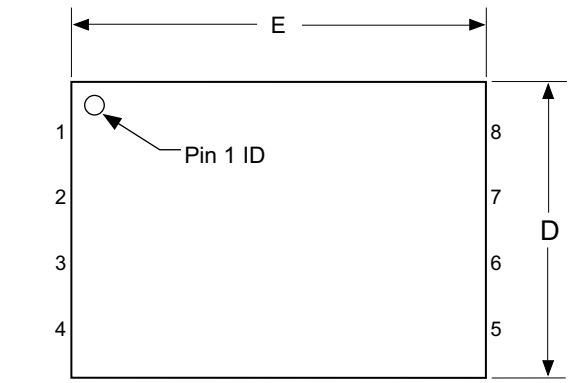
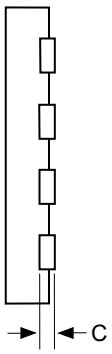
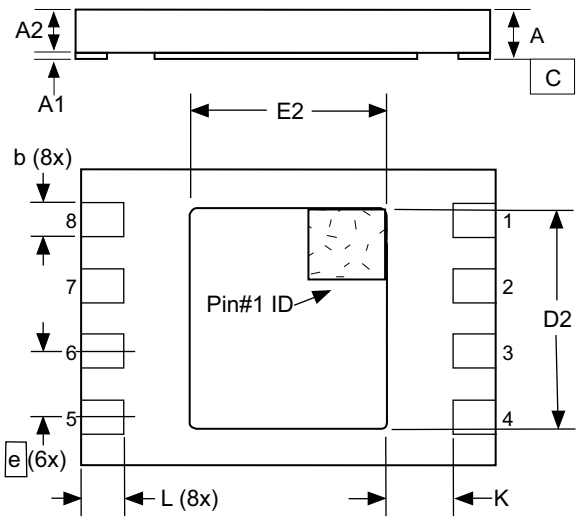
9.3 8MA2 — 8-pad UDFN



TOP VIEW



SIDE VIEW



BOTTOM VIEW

Notes:
1. This drawing is for general information only. Refer to Drawing MO-229, for proper dimensions, tolerances, datums, etc.
2. The Pin #1 ID is a laser-marked feature on Top View.
3. Dimensions b applies to metallized terminal and is measured between 0.15 mm and 0.30 mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal, the dimension should not be measured in that radius area.
4. The Pin #1 ID on the Bottom View is an orientation feature on the thermal pad.

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.50	0.55	0.60	
A1	0.0	0.02	0.05	
A2	-	-	0.55	
D	1.90	2.00	2.10	
D2	1.40	1.50	1.60	
E	2.90	3.00	3.10	
E2	1.20	1.30	1.40	
b	0.18	0.25	0.30	3
C	0.152 REF			
L	0.35	0.40	0.45	
e	0.50 BSC			
K	0.20	-	-	

11/2/15

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE 8MA2, 8-pad 2 x 3 x 0.6mm Body, Thermally Enhanced Plastic Ultra Thin Dual Flat No-Lead Package (UDFN)	GPC YNZ	DRAWING NO. 8MA2	REV. H

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10. Revision History

Doc. Rev.	Date	Comments
8810E	09/2016	Added the Automotive Grade 2 and 3 options and UDFN options.
8810D	06/2015	Updated ordering codes tables and Section 7.1, part marking information, 8S1 and 8X package drawings, and footers.
8810C	12/2012	Updated ordering code tables and the 8X package drawing.
8810B	08/2012	Removed preliminary status. Updated Atmel logos and disclaimer/copy page.
8810A	04/2012	Initial document release.

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